

nRF8002

Single-chip *Bluetooth*® Low Energy Proximity Solution

Product Specification 1.1

Key Features

- Fully qualified *Bluetooth* low energy 4.0 peripheral device
- Single chip solution for *Bluetooth* low energy proximity applications
- Integrated *Bluetooth* low energy profiles and services
- Configurable I/Os for application behavior
- Ultra-low power consumption
- Coin-cell battery operation
- Low cost 16 MHz ± 50 ppm crystal
- On-chip 32 kHz RC oscillator
- Single 1.9-3.6 V power supply
- Low cost external BOM
- Temperature range -25 to +70°C
- Compact 5x5 mm QFN32 package
- RoHS compliant

Applications

- Proximity applications
- Key fobs
- Watches

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Datasheet status	
Objective Product Specification	This product specification contains target specifications for product development.
Preliminary Product Specification	This product specification contains preliminary data; supplementary data may be published from Nordic Semiconductor ASA later.
Product Specification	This product specification contains final product specifications. Nordic Semiconductor ASA reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

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Revision History

Date	Version	Description
September 2013	1.1	- Updated section 10.1 on page 35 and chapter 15 on page 43. - Fixed minor issues throughout the document.
August 2012	1.0	- First release of the Product Specification (PS). - Renamed pin 32 from DCC to NC, see Figure 2. on page 7. - Changed application behavior, when the peer terminates the connection, the nRF8002 goes into connecting state, see Figure 4. on page 11. - Added chapter 2 on page 6, <i>Bluetooth</i> Qualification ID. - Added section 6.4 on page 29, Configuration in production - Fixed minor issues throughout the document.
February 2012	0.7	First release of the Preliminary Product Specification (PPS)

Contents

1	Introduction	5
2	Bluetooth Qualification ID	6
3	Pin assignment	7
3.1	Pin functions	8
4	Operation	9
4.1	Power up	9
4.2	Power up sequence flow chart	10
4.3	State diagram	11
5	nRF8002 profiles and services	12
5.1	Generic Access Profile (GAP) parameters	12
5.2	Profiles and services	12
6	nRF8002 configuration	14
6.1	Profile and Service configuration	14
6.2	Input Signals (ISIG)	17
6.3	Output signals (OSIG)	20
6.4	Configuration in production	29
7	Direct Test Mode (DTM)	32
7.1	Activating and deactivating Direct Test Mode	32
7.2	Transmitter constant carrier operation	32
8	Absolute maximum ratings	33
9	Operating conditions	34
10	Electrical specifications	35
10.1	Digital I/O signal levels	35
10.2	Radio characteristics	36
10.3	Analog feature characteristics	37
11	Current consumption	38
12	Hardware description	39
12.1	Reset	39
12.2	16 MHz oscillator	39
12.3	UART interface characteristics	40
12.4	Antenna matching and balun	40
12.5	PCB layout and decoupling guidelines	40
13	Mechanical specifications	41
14	Ordering information	42
14.1	Package marking	42
14.2	Abbreviations	42
14.3	Product options	42
15	Example application circuitry	43
15.1	PCB guidelines	43
15.2	Schematic nRF8002 example application	43
15.3	PCB layout nRF8002 example application	44
15.4	Bill of Materials nRF8002 example application	45
16	Glossary	46

1 Introduction

nRF8002 is a single-chip *Bluetooth* low energy peripheral device for proximity solutions.

With a complete *Bluetooth* low energy stack along with Proximity, Find Me and, Alert Notification profiles, nRF8002 fulfills the needs for simple phone and PC accessories. It can alert you if your devices go out of range, enable security features like screen lock and give you notice of new events like incoming mail, SMS and, calls. nRF8002 also embeds a configurable application allowing you to use nRFgo Studio to configure device and I/O behavior. The I/O can interface directly with user input and output devices such as buttons, LEDs, buzzers, or vibrators.

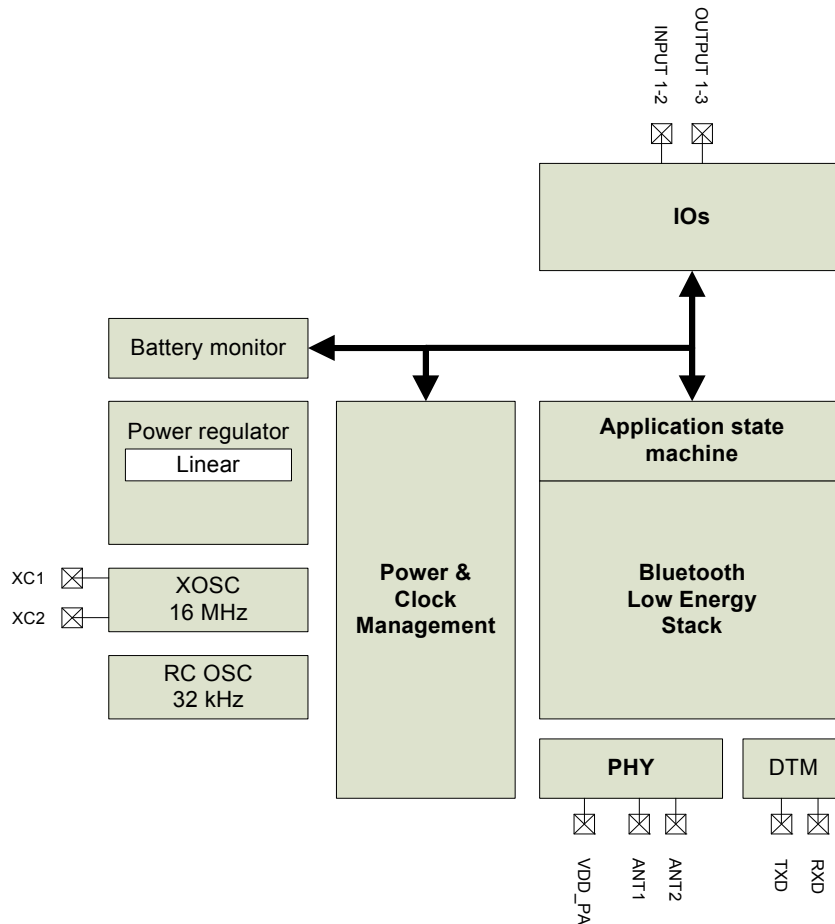


Figure 1. nRF8002 block diagram

2 **Bluetooth Qualification ID**

nRF8002 is listed as an EP-QDL on the Qualified listings page of the *Bluetooth* Special Interest Group website <https://www.bluetooth.org/tpg/listings.cfm>.

For details on the design qualifications, please refer to the following qualification IDs:

- B019507 - nRF8002, End Product, Single-chip *Bluetooth* low energy proximity solution.
- B019124 - uBlue Host 1.2, Nordic *Bluetooth* Low Energy Host Layer version 1.2.
- B016981 - Nordic µBlue LL, BTLE link layer stack component.
- B019518 - nRF8002_RF, *Bluetooth* low energy HW platform containing the RF PHY layer for the nRF8002 system on chip device.

3 Pin assignment

nRF8002 is available in a 5x5 mm QFN32 package. The back plate of the QFN32 capsule must be grounded to the application PCB in order to achieve optimal performance. The physical dimensions of the QFN32 are presented in chapter [13 on page 41](#).

[Figure 2.](#) shows the pin assignment for nRF8002 and [Table 1. on page 8](#) describes the pin functionality.

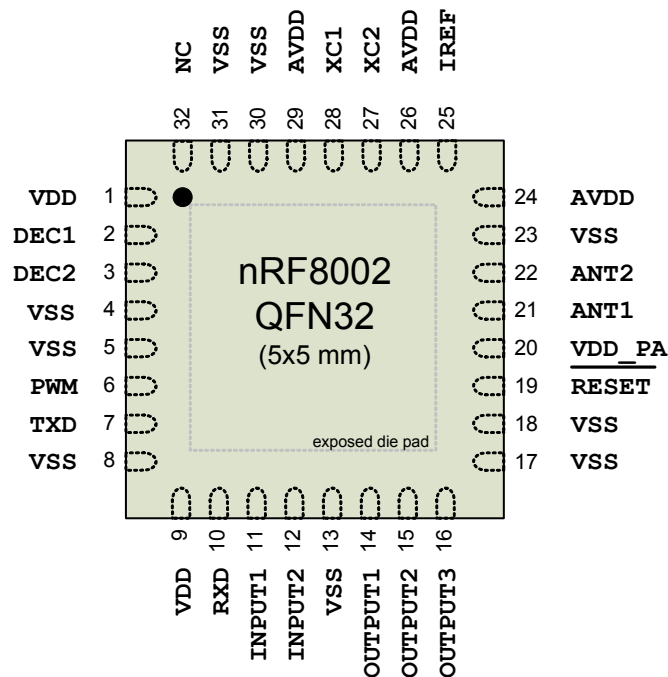


Figure 2. nRF8002 pin assignment (top view)

3.1 Pin functions

Pin	Pin name	Pin functions	Description
1	VDD	Power	Power supply (1.9 – 3.6 V)
2	DEC1	Power	Regulated power supply output for decoupling purposes only. Connect 100 nF capacitor to ground
3	DEC2	Power	Regulated power supply output for decoupling purposes only. Connect 33 nF capacitor to ground
4	VSS	Power	Ground (0V)
5	VSS	Power	Ground (0V)
6	PWM	Digital output	Programmable PWM output (range 490 Hz....516 kHz)
7	TXD	Digital output	UART (transmit) for <i>Bluetooth</i> low energy Direct Test Mode Interface and for configuration download. After final OTP program of configuration, pin must be set to VSS.
8	VSS	Power	Ground (0V)
9	VDD	Power	Power supply (1.9 – 3.6 V)
10	RXD	Digital input	UART (receive) for <i>Bluetooth</i> low energy Direct Test Mode Interface and for configuration download. After final OTP program of configuration, pin must be set to VSS.
11	INPUT1	Digital input	General input (if not in use this pin must be set to VSS)
12	INPUT2	Digital input	General input (if not in use this pin must be set to VSS)
13	VSS	Power	Ground (0V)
14	OUTPUT1	Digital output	General output
15	OUTPUT2	Digital output	General output
16	OUTPUT3	Digital output	General output
17	VSS	Power	Ground (0V)
18	VSS	Power	Ground (0V)
19	RESET	Digital input	Reset (active low)
20	VDD_PA	Power output	Regulated power supply output for on-chip RF Power amplifier
21	ANT1	RF	Differential antenna connection (TX and RX)
22	ANT2	RF	Differential antenna connection (TX and RX)
23	VSS	Power	Ground (0V)
24	AVDD	Power	Analog power supply (1.9 – 3.6 V DC)
25	IREF	Analog output	Current reference terminal. Connect a 22 kΩ 1% resistor to ground
26	AVDD	Power	Analog power Supply (1.9 – 3.6 V)
27	XC2	Analog output	Connection for 16 MHz crystal oscillator. Leave unconnected if not in use
28	XC1	Analog input	Connection for 16 MHz crystal or external 16 MHz reference
29	AVDD	Power	Analog power supply (1.9 – 3.6 V DC)
30	VSS	Power	Ground (0V)
31	VSS	Power	Ground (0V)
32	NC	-	Not connected
Exposed die pad	VSS	Power	Ground (0V), connect to VSS

Table 1. nRF8002 pin functions

4 Operation

This chapter describes the power-up sequence for nRF8002 and the modes it can enter and also a state diagram that illustrates the operating states and their behavior. Configuration data can be stored in RAM or non-volatile memory (also called One Time Programmable memory, or OTP) in nRF8002.

4.1 Power up

Power up is defined as when nRF8002 is powered up for the first time (the battery is inserted) or the chip is reset. When nRF8002 is powered up its behavior depends on whether a custom configuration has been pre-programmed into the non-volatile memory (OTP). If the OTP contains a valid configuration, nRF8002 starts with these configuration settings and is ready for operational use.

In Configuration mode, nRF8002 can receive the configuration generated by nRFgo Studio. The nRF8002 configuration decides profile, application and I/O behavior. RAM is used during development to enable repeated configuration downloads. Each time nRF8002 is reset, or power is removed, it returns to a non-configured state and you can choose to enter DTM or download a new configuration.

If there is no valid configuration available in OTP, nRF8002 will start in either Direct Test Mode (DTM) or Configuration mode, depending on the first byte received on the UART:

- If the first byte received on the UART is `0xFF`, nRF8002 starts in Configuration mode.
- If the first byte received on the UART is NOT `0xFF`, nRF8002 starts in DTM mode.
See chapter [7 on page 32](#) for more information on DTM.

Note: When the chip is in DTM or Configuration mode it will rapidly drain the battery, as it does not use power management in these modes.

Once development is finished final configuration can be downloaded to non-volatile memory (OTP) from nRFgo studio or saved to file for use in factory programming tools.

Note: If configuration is programmed into OTP, DTM mode is no longer accessible.

When the configuration is available in OTP, the UART is disabled.

4.2 Power up sequence flow chart

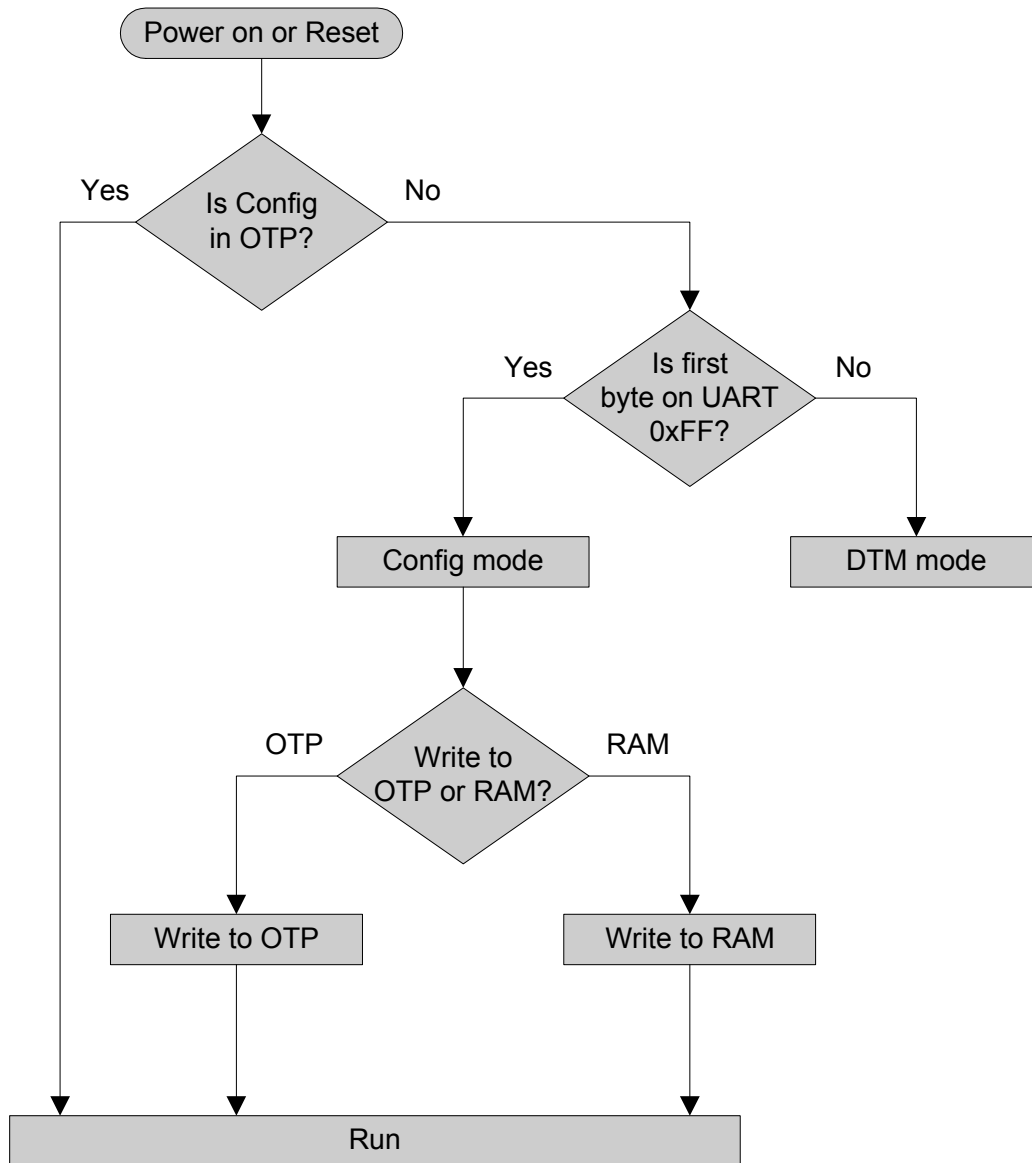


Figure 3. Power up sequence flow chart

4.3 State diagram

Figure 4. defines nRF8002's different operating states and their behavior. For details on the configuration parameters, see chapter 8 on page 33.

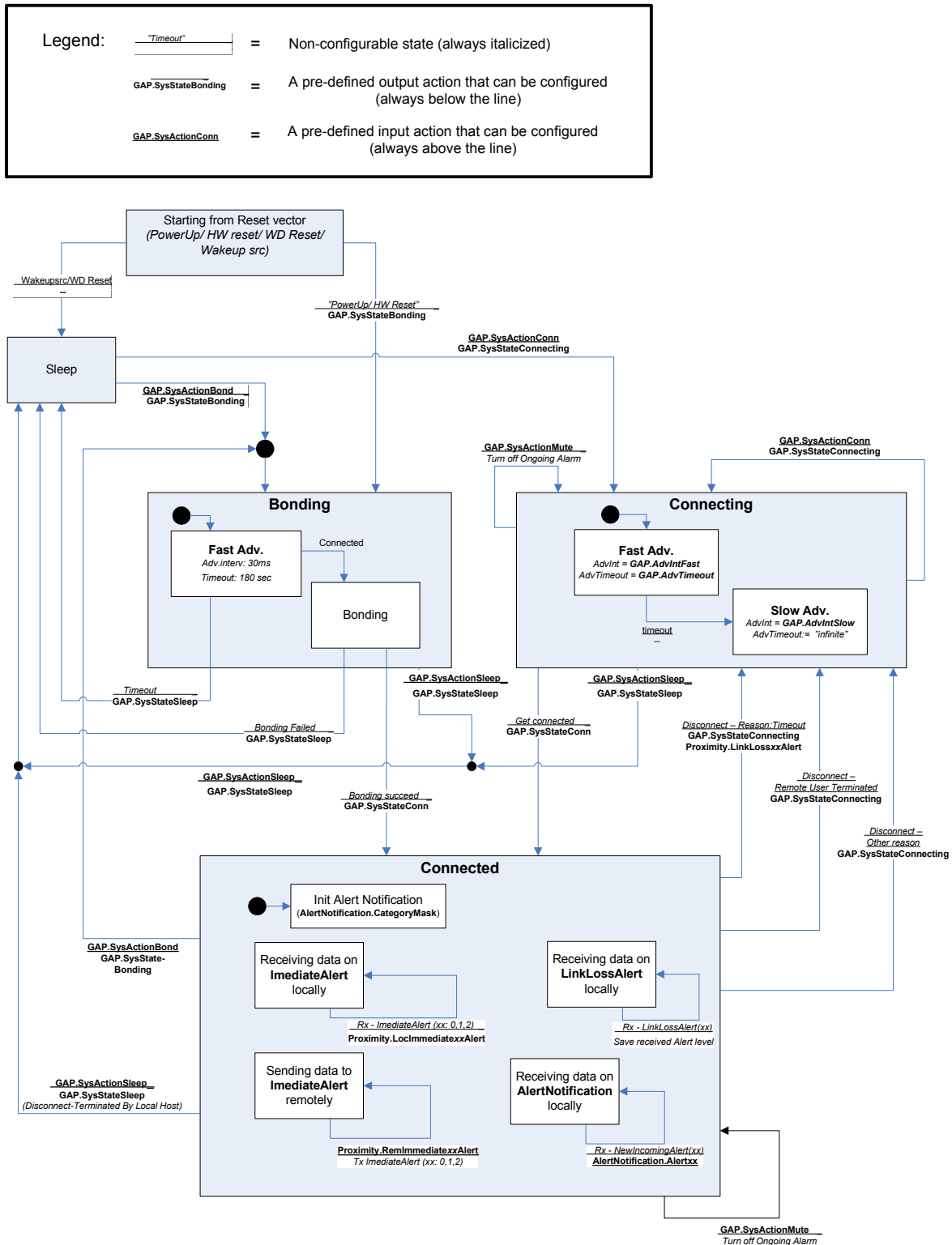


Figure 4. State diagram

5 nRF8002 profiles and services

nRF8002 offers Battery Status, TX power, Link Loss and, Immediate Alert services. It also implements the Find Me and Alert Notification profiles for use with a peer device that supports Alert Notification and Immediate Alert services. When a connection is established with a peer device, nRF8002 automatically performs the service discovery and enables the corresponding application functionality.

5.1 Generic Access Profile (GAP) parameters

nRF8002 implements the Generic Access Profile (GAP) using the following parameters, (see chapter [6.1 on page 14](#) for more information):

- Configurable advertising intervals
- Device name characteristic
- Device security: Just Works
- Minimum encryption key size: 7 bytes
- Maximum encryption key size: 16 bytes
- TX power
- Preferred peripheral connection parameters characteristic

When a connection is established but the connection interval is not within the set parameters, nRF8002 responds by initiating the Connection Parameter Update procedure as described in the *Bluetooth Core Specification Ver. 4.0, Vol. 3.0, Part C, GAP, section 9.3.9*. If the peer does not change the connecting interval, nRF8002 will disconnect.

5.2 Profiles and services

This section describes the services that are available on nRF8002, and the services it will try to discover on a peer device.

5.2.1 nRF8002 local services

The service and characteristics that are available on nRF8002 are defined in [Table 2](#) below.

Attribute type	UUID	Value	Properties
Primary Service	0x2800	GAP (0x1800)	Read
Characteristic Declaration	0x2803	Device Name (0x2A00)	Read
Characteristic Value - Device Name	0x2A00	"nRF8002"	Read/Write
Characteristic Declaration	0x2803	Appearance (0x2A01)	Read
Characteristic Value - Appearance	0x2A01	0x0000	Read
Characteristic Declaration	0x2803	PPCP (0x2A04)	Read
Characteristic Value – PPCP	0x2A04	Conn _{min} , Conn _{max} , Slave Latency, Timeout	Read
Primary Service	0x2800	GATT (0x1801)	Read
Primary Service	0x2800	DEVICE INFORMATION (0x180A)	Read
Characteristic Declaration	0x2803	Manufacturer Name (0x2A29)	Read
Characteristic Value – Manufacturer Name	0x2A29	"NordicSemi"	Read
Characteristic Declaration	0x2803	Model Number (0x2A24)	Read
Characteristic Value – Model Number	0x2A24	"nRF8002"	Read
Characteristic Declaration	0x2803	Firmware revision (0x2A26)	Read

Attribute type	UUID	Value	Properties
Characteristic Value – Firmware revision	0x2A26	This will be set to the nRF8002 firmware version number	Read
Characteristic Declaration	0x2803	Software revision (0x2A28)	Read
Characteristic Value – Software revision	0x2A28	Configurable by nRFgo Studio	Read
Primary Service	0x2800	IMMEDIATE ALERT (0x1802)	Read
Characteristic Declaration	0x2803	Alert Level (0x2A06)	Read
Characteristic Value – Alert Level	0x2A06	<Value>	Read/ WriteWithoutResponse
Primary Service	0x2800	LINK LOSS (0x1803)	Read
Characteristic Declaration	0x2803	Alert Level (0x2A06)	Read
Characteristic Value – Alert Level	0x2A06	<Value>	Read/Write
Primary Service	0x2800	TX POWER (0x1804)	Read
Characteristic Declaration	0x2803	TxPower (0x2A07)	Read
Characteristic Value – TxPower	0x2A07	<0x00>	Read
Primary Service	0x2800	BATTERY (0x180F)	Read
Characteristic Declaration	0x2803	BatteryLevel (0x2A19)	Read
Characteristic Value – BatteryLevel	0x2A19	0x64 (=100%)	Read/Notify
Char Descriptor - CCCD	0x2902	< Configuration>	Read/Write

Table 2. Services and characteristics on nRF8002

5.2.2 nRF8002 profiles and remote services

nRF8002 automatically carries out service discovery on a peer device and attempts to discover the services defined in [Table 3](#).

Attribute type	UUID	Value	Properties
Primary Service	0x2800	GATT (0x1801)	Read
Characteristic Declaration	0x2803	Service Changed (0x2A05)	Read
Characteristic Value – Service Changed	0x2A05	<... Service change values ...>	Indicate
Char Descriptor – CCCD	0x2902	<Configuration>	Read/ Write
Primary Service	0x2800	IMMEDIATE ALERT (0x1802)	Read
Characteristic Declaration	0x2803	Alert Level (0x2A06)	Read
Characteristic Value – Alert Level	0x2A06	<Value>	Read/ WriteWithoutResponse
Primary Service	0x2800	ALERT NOTIFICATION (0x1811)	Read
Characteristic Declaration	0x2803	Supported New Alert Category (0x2A47)	Read
Characteristic Value – Supported New Alert Category	0x2A47	<Value>	Read
Characteristic Declaration	0x2803	New Alert (0x2A46)	Read
Characteristic Value – New Alert	0x2A46	<0x00>	Notify
Char Descriptor – CCCD	0x2902	<Configuration>	Read/ Write
Characteristic Declaration	0x2803	Alert Notification Control Point (0x2A44)	Read
Characteristic Value – Alert Notification Control Point	0x2A44	<0x00>	Write

Table 3. Supported services/characteristics on a peer device

6 nRF8002 configuration

Profiles and services are pre-defined on nRF8002 but, you can configure input signals to generate pre-defined GAP behavior and pre-defined actions related to Profiles and Services. Output signals can be configured to generate patterns on pre-defined events that are related to Services, Profiles and, GAP behavior.

nRF8002 must be configured using the nRFgo Studio v1.12.3 or later. The configuration is downloaded through the UART, either directly from nRFgo Studio or by using the Production configuration tool available from Nordic Semiconductor. When downloading, you can choose to load the configuration into volatile memory (RAM) for development purposes or non-volatile memory (OTP) for production.

Note: If loaded into non-volatile memory (OTP) you cannot reconfigure nRF8002.

nRF8002 can be configured to respond to different input pin pulses and to issue different output patterns depending on the *Bluetooth* service and profile behavior.

Use the nRF8002 configuration tool in nRFgo Studio to change and download new configurations that match your application needs by setting the configuration in RAM. A default configuration is available in nRFgo Studio for download to your nRF8002 device. The default configuration is made to work with the development kit.

6.1 Profile and Service configuration

nRF8002 contains an integrated set of *Bluetooth* profiles and services. The application behavior of these profiles and services can be connected to Input signal (ISIG) and Output signal (OSIG) events.

6.1.1 General settings

6.1.1.1 Generic Access Profile (GAP) and hardware settings

nRF8002 allows the following configuration of hardware and GAP settings through the nRFgo Studio:

Name	Resolution	Description
GAP.LocalName	N/A	Local Name of the device: 0 - 20 bytes (UTF-8 sting) (no null termination)
GAP.Appearance	N/A	Appearance characteristic
GAP.TxPowerConn	N/A	Output Power of nRF8002 in connection or advertising to a bonded device, Steps: -18, -12, -6, 0 dBm
GAP.AdvIntSlow	625 μ s	Background advertising Interval - Slow Adv. n – Background (Range:32...16384)
GAP.AdvIntFast	625 μ s	Fast advertising Interval - Fast Adv. n – Fast (Range: 32...16384)
GAP.AdvTimeout	1 s	Timeout for Fast Adv. Up to 180 sec, 1 sec resolution. Only available in connecting state.
GAP.ConnIntMin	1.25 ms	Minimum Connection Interval: 250 ms – 2 sec, must be less than GAP.ConnIntMax
GAP.ConnIntMax	1.25 ms	Maximum connection Interval: 250 ms – 2 sec, must be more than GAP.ConnIntMin + 12.5 ms
GAP.ConnTimeout	1.25 ms	Connection Supervision Timeout.

Table 4. GAP and hardware configuration settings

6.1.1.2 GAP state to OSIG configuration

nRF8002 allows the following configuration of OSIG events when entering the different states defined in GAP through the nRFgo Studio:

Name	Action
GAP.SysStateBonding	Output Pin, pattern number, inverted, enable/disable
GAP.SysStateConnecting	Output Pin, pattern number, inverted, enable/disable
GAP.SysStateConnected	Output Pin, pattern number, inverted, enable/disable

Table 5. GAP state to OSIG Configuration

6.1.1.3 GAP state to ISIG configuration

nRF8002 allows the following configuration of ISIG events to enter different GAP states through the nRFgo Studio:

Name	Action
GAP.SysActionBond	Input pin, Press Event
GAP.SysActionConnecting	Input pin, Press Event
GAP.SysActionSleep	Input pin, Press Event
GAP.SysActionMute	Input pin, Press Event

Table 6. GAP state to ISIG Configuration

6.1.2 Profiles

6.1.2.1 Device information settings

nRF8002 allows the following configuration of Device Information settings through the nRFgo Studio:

Name	Units	Description
DeviceInfo.ManufacturerName	n/a	The name of the manufacturer of the device 0 - 20 bytes (no null termination)
DeviceInfo.ModelNumber	n/a	The model number that is assigned by the device vendor 0 - 20 bytes (no null termination)
DeviceInfo.FirmwareRevision	n/a	The firmware revision of the nRF8002 device (this is non-configurable)
DeviceInfo.SoftwareRevision	n/a	The Software revision of the device

Table 7. Description of device information settings

6.1.2.2 nRF8002 profile and service behavior to OSIG configuration

The Proximity Alert settings (OSIG) define the output pins that are triggered on the different alarms.

Name	Action
Proximity.LinkLossMildAlert	Output pin, pattern number, inverted, enable/disable. Link Loss with Mild Alert active.
Proximity.LinkLossHighAlert	Output pin, pattern number, inverted, enable/disable. Link Loss with High Alert active.
Proximity.LocImmediateOffAlert	Output pin, pattern number, inverted, enable/disable. Local Off Alert.
Proximity.LocImmediateMildAlert	Output pin, pattern number, inverted, enable/disable. Local Mild Alert.
Proximity.LocImmediateHighAlert	Output pin, pattern number, inverted, enable/disable. Local High Alert.
AlertNotification.CategoryMask	See Alert Notification Service (0 disables all alerts) (UINT16 bit mask).
AlertNotification.Alert 1	AlertCategory Id bit mask to set which Category that should trigger this OSIG.
...	
AlertNotification.Alert 4	AlertCategory Id bit mask to set which Category that should trigger this OSIG.

Table 8. Profile and service behavior to OSIG Configuration (OSIG)

6.1.2.3 nRF8002 profile and service behavior to ISIG configuration

The Proximity signaling actions (ISIG) define which input signals should be used to send an alarm:

Name	Description
Proximity.RemImmediateOffAlert	Input pin, Press Event Trigger Remote Off Alert
Proximity.RemImmediateMildAlert	Input pin, Press Event Trigger Remote Mild Alert
Proximity.RemImmediateHighAlert	Input pin, Press Event Trigger Remote High Alert

Table 9. Profile and service behavior to ISIG Configuration (ISIG)

6.1.2.4 Battery configuration

The battery voltage level defines when an alarm will be triggered:

Name	Resolution	Description
HW.BatteryVoltageLevel0	3.52 mV	Voltage corresponding to battery 80% (Everything above will get reported as 100%) (BatteryState = Good Level)
HW.BatteryVoltageLevel1	3.52 mV	Voltage corresponding to battery 60% (BatteryState = Good Level)
HW.BatteryVoltageLevel2	3.52 mV	Voltage corresponding to battery 40% (BatteryState = Good Level)
HW.BatteryVoltageLevel3	3.52 mV	Voltage corresponding to battery 20%. (BatteryState = Critically Low Level)
HW.Battery_40_percent	OSIG	Output signal generated when battery level is reaching 40%.
HW.Battery_20_percent	OSIG	Output signal generated when reaching battery level is reaching 20%.

Table 10. Battery configuration

6.1.2.5 Mute

The mute action lets a user stop a OSIG event (for example, to silence an audible alarm). You can configure which input signal generates the mute action and which Output signal(s) that is turned off by this action.

The mute action is only available when nRF8002 is in connected mode.

6.2 Input Signals (ISIG)

Two input pins (ISIG) can be configured on nRF8002.

6.2.1 Configuration of the Input Signal (ISIG)

Through configuring the Input Signals (ISIG), they can be converted into events used to control behavior on nRF8002.

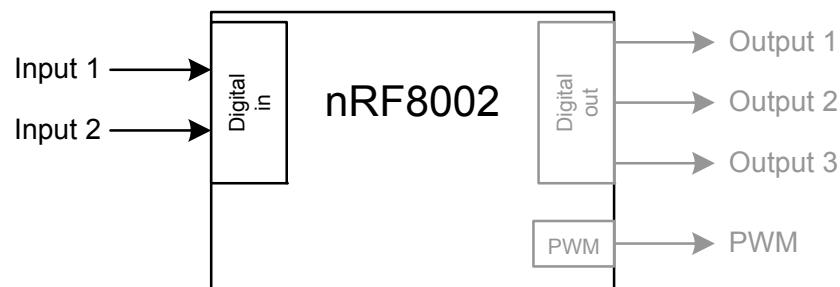


Figure 5. Block diagram showing the input pins

6.2.2 Input polarity

The input polarity can be set individually for each of the input pins. [Table 11](#). below describes the expected behavior (Input Signal).

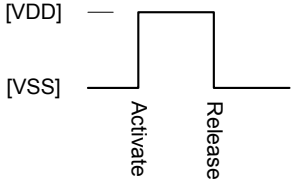
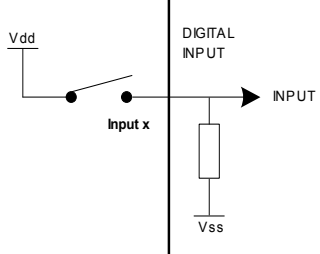
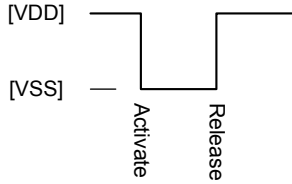
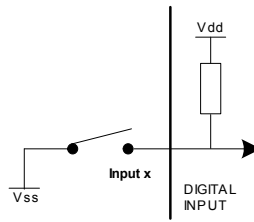
Polarity	Input signal	Schematic	Description
Active High			The input line is initiated by a VSS-to-VDD transition. The input pin is configured to logic level 0 using an internal pull down resistor.
Active Low			The input line is initiated by a VDD-to-VSS transition. The input pin is configured to logic level 1 using an internal pull up resistor.

Table 11. Input signal behavior

6.2.3 Events generated from the inputs

Each input line can generate the following four events:

- Activation Trigger Event
- Short Press Event
- Medium Press Event
- Long Press Event

The Activation Trigger Event is generated every time the input line is activated (see section [6.2.2 on page 18](#)). Depending on the time it takes before the input line is released (length of the pulse), nRF8002 will generate one of three events: a Short, Medium, or a Long press event. Minimum time before an input is released is 50 ms, for detection of a valid trigger and subsequently a press event.

For nRF8002 to distinguish between these three events, the user has to specify two timer values, as defined in [Table 12](#). The two timer values are common for both input lines.

Timer	Description
t1	Distinguishes between a short and a medium press.
t2	Distinguishes between a medium and a long press.

Table 12. Timer values

Decoding an input pulse using t_1 and t_2 will generate the following event:

- All pulses will generate an Activation Trigger event at the start of the pulse.
- An input pulse that has ended before reaching t_1 will be decoded as a Short Press.
- An input pulse that is active when reaching t_1 but has ended before reaching t_2 will be decoded as a Medium Press.
- An input pulse that is active when reaching t_2 will be decoded as Long Press.

6.2.4 OSIG events generated by the inputs

Generating an OSIG event from an input signal is a good way to give a user feedback that is related to the length of the pulse they have activated.

Each of the two input lines on the device has two OSIG events. The first OSIG event is generated when the input line has been active for a period equal to t_1 , the second OSIG event is generated when the input line has been active for a period equal to t_2 .

See [Table 14. on page 21](#) for a list of the events. For configuration of the OSIG events see section [6.3.5 on page 27](#), OSIG activation.

6.2.4.1 Example showing ISIG event and OSIG action

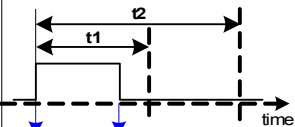
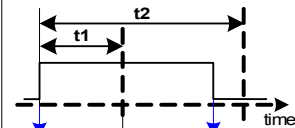
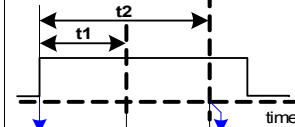
Input pulse		Description
Short Press 	ISIG Events: Edge trig Short press	• Input pulse shorter than t_1. • Gives an Activation trigger event at the start of the pulse. • Gives a Short Press Event at the end of the pulse. • OSIG Activation: none.
	OSIG Activation:	
Medium Press 	ISIG Events: Edge trig Medium press	• Input pulse longer than t_1, but shorter than t_2. • Gives an Activation trigger event at the start of the pulse. • OSIG Activation: Input x - t_1 when the time t_1 is reached. • Gives a Medium Press Event at the end of the pulse.
	OSIG Activation: Input x - t_1	
Long Press 	ISIG Events: Edge trig Long press	• Input pulse longer than t_2. • Gives an Activation trigger event at the start of the pulse. • OSIG Activation: Input x - t_1 when the time t_1 is reached. • OSIG Activation: Input x - t_2 when the time t_2 is reached. • Gives a Long Press Event at the end of the pulse.
	OSIG Activation: Input x - t_1 Input x - t_2	

Table 13. ISIG event and OSIG activation from Activation trigger and short, medium and, long press

6.3 Output signals (OSIG)

Four Output signals (OSIG), one of which is a PWM, can be configured on nRF8002. An Output signal (OSIG) is a Pulse Train pattern set on one of the four output pins.

6.3.1 Configuration of the Output signal (OSIG)

This section describes how the output ports are controlled by the configuration. The configuration of the output signals is defined as a Pulse Train and is defined by t_1 , t_2 and, n_t as documented in section [6.3.4 on page 23](#). The Pulse Train can be configured to repeat and is then defined as a Repeated Pulse Train. The action generating the OSIG is configurable and is linked to GAP, profile or, service behavior.

nRF8002 has four output ports where port 1 to 3 are digital outputs and port 4 is a PWM output, see [Figure 6](#).

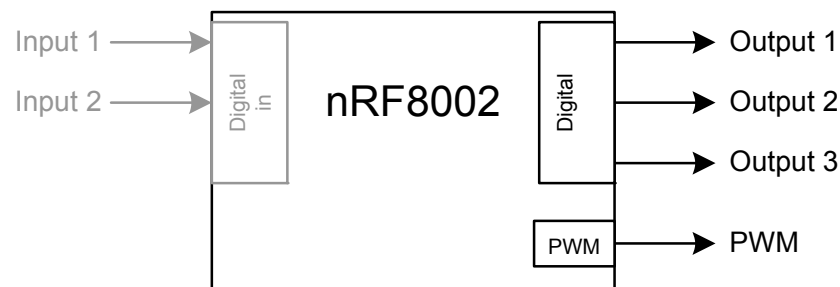


Figure 6. nRF8002's output ports

As shown in [Figure 7. on page 21](#), the output logic is divided into four different modules:

- OSIG Pattern: a set of logical pulse patterns that can be used to generate signals on the output ports.
- OSIG Activation: translates events into OSIG actions.
- Output Handler: the engine that receives instructions from the OSIG Activation and uses this together with the OSIG Pattern and the timer ticks to generate output action.
- OSIG Output logic: translates the logical ON/OFF command received from the Output handler into voltage level on the output ports. It also controls the PWM output signal.

Note: The OSIG Pattern, Activation, and Handler modules handle logical ON/OFF signals. The OSIG Output logic module translates the logical signal into a voltage level. This is done to separate the logical behavior from the physical representation on the output port.

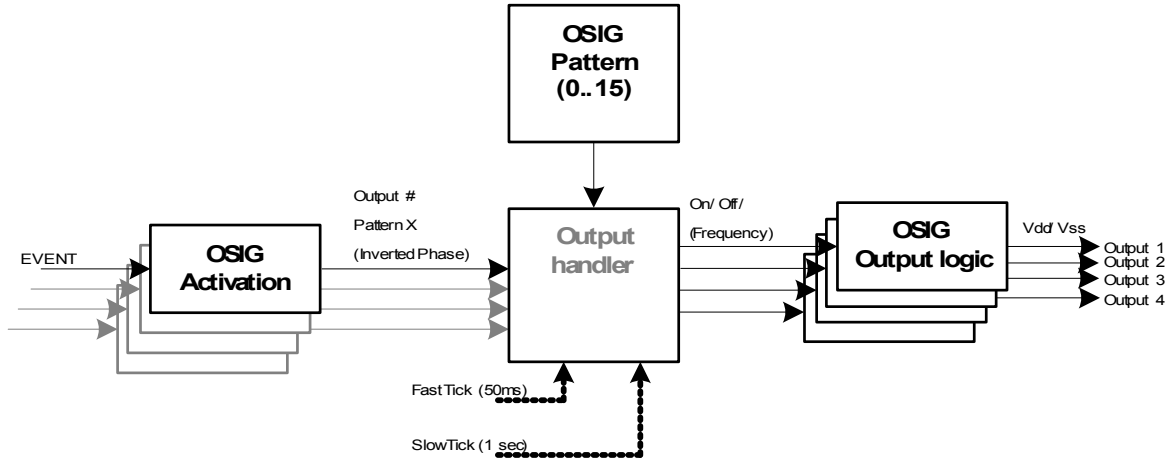


Figure 7. Output logic modules

6.3.2 Event table

Table 14. lists all the events that the user can configure to give an OSIG Activation.

Event	Description
Sleep State ¹	An event is generated when nRF8002 enters the given state.
Bond State	
Connecting State	
Connected State	
Link Loss Mild Alert	One of these events could be generated when nRF8002 detects a link loss with <i>Timeout</i> . Which of the events depends on the Link Loss alert level set by the peer device.
Link Loss High Alert	
Immediate Alert – No Alert	An event is generated when nRF8002 receives the corresponding Immediate Alert from the peer device.
Immediate Alert – Mild Alert	
Immediate Alert – High Alert	
Battery Level 40%	Events are generated every 10 minutes as long as the battery is on the actual level.
Battery Level 20%	
Alert Notification 0	Events are generated when nRF8002 receives an Alert Notification that matches the configuration set for the Alert Notification (See 6.1.2.2 on page 16).
Alert Notification 1	
Alert Notification 2	
Alert Notification 3	
ISIG – Mute Action	This event is generated by a ISIG event (as configured by the user)
ISIG Input 1 – t1	These events are given when the input port has been kept active for a period equal to the timer value (Used for giving feedback on a button press)
ISIG Input 1 – t2	
ISIG Input 2 – t1	
ISIG Input 2 – t2	

1. This event is hard-coded to turn OFF all output ports.

Table 14. Event table

6.3.3 OSIG output logic

The OSIG output logic is set individually for each of the four ports and specifies the translation from the logical representation (ON/OFF) to the voltage level (VDD/VSS). It specifies whether the logical value ON should set the port to high (VDD) or low (VSS).

For the PWM output port the frequency output will be set with 50% duty cycle when the port is ON. The first pulse will always be high (VDD).



Figure 8. Output logic on the digital and PWM ports

Figure 9. illustrates the behavior on the output pin related to the actual setting. The first row describes the behavior when the output is set to active high. Both the digital and the PWM output will then be set to VSS on Reset (power-up) and when it is set to OFF. When the output port is set ON the digital output will switch from VSS to VDD, while the PWM output will start oscillating at the specified frequency.

The second row in Figure 9. shows the reverse active low polarity.

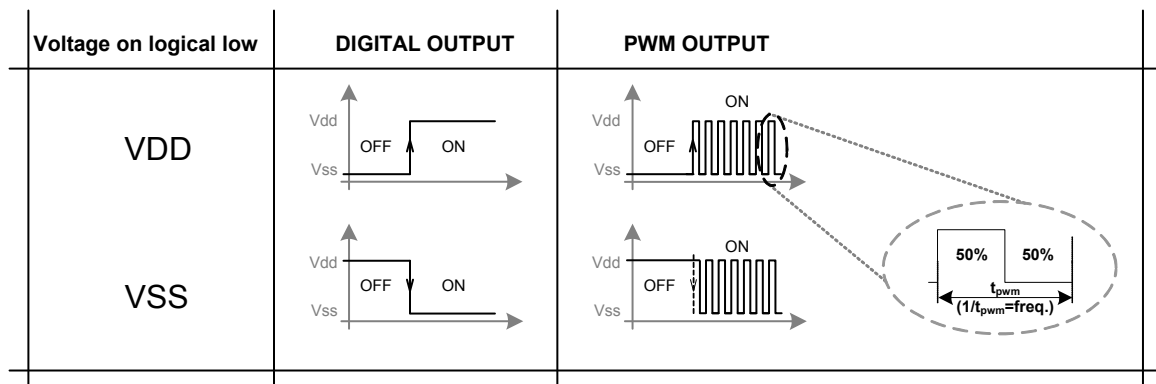


Figure 9. PWM output voltage on active high and active low

6.3.4 OSIG pattern

The OSIG pattern is a table where the you can specify up to 15 different output patterns numbered from 1 to 15. It is also possible to invert a pattern during OSIG activation, see also [Table 20. on page 27](#)

Pattern 0 is predefined to a fixed level used to set the pin either permanently ON or OFF.

No.	t_{p1}	t_{p2}	n_p	t_t	n_t	f_{pwm}	Description
0	1	0	0	0	0	0	Pre-configured to ON (OFF)
1							Up to 15 patterns that should be configured by the customer
2							
...							
14							
15							

Table 15. Output patterns

The pattern specification is independent of the different output ports, that is, all patterns could be used on all the outputs.

The OSIG pattern is specified using timers (t_{xx}) and counters (n_x). In addition, there is an optional parameter [f_{pwm}] that specifies the frequency to be used in the ON period for the PWM output (Output port 4). This parameter will be ignored if the pattern is used on a digital output, but has to be specified for all patterns used on PWM.

The OSIG pattern can be specified using two different modes: Fast Tick or Slow Tick mode. The difference between them is the resolution for the two timers [t_{p1}] and [t_{p2}] that specifies the ON and OFF period.

Table 16. shows timers and counters that are defined as part of the OSIG Pattern definition:

Parameter	Value range	Description
t_{p1}	50 ms...12.75 sec ¹ 1 sec...4 min15 sec ¹ .	Defines the period for when the output should be ON.
t_{p2}		Defines the period for when the output should be OFF.
n_p	1..127 or ∞	Defines number of times the ON-OFF period, given by $[t_{p1}]/[t_{p2}]$, should be repeated (i.e. <i>Pulse Train</i> = $n_p * ([t_{p1}] + [t_{p2}])$. If $[n_p]$ is set to $[\infty]$ (infinite) the ON-OFF period will be repeated forever. For $[n_p] = 1$ or $[n_p] = [\infty]$ the parameters $[t_i]$ and $[n_i]$ are not applicable.
t_t	1..255	Delay, given in seconds, between the start of two consecutive <i>Pulse Trains</i> . This delay shall be set to a value longer than the time it takes for one <i>Pulse Train</i> to complete, i.e $[t_t] > (n_p * [t_{p1}/t_{p2}])$.
n_t	1..127 or ∞	Number of times the <i>Pulse Train</i> should be repeated before it sets the output to OFF. If $[n_t]$ is set to $[\infty]$ (infinite) the <i>Pulse Train</i> will be repeated forever. This pattern will be activated on the next 1 sec tick (i.e. activation could be delayed up to 1 sec). For $[n_t] = 1$ parameters $[t_i]$ are not applicable.
f_{pwm}	490 Hz – 516 kHz	Frequency to be used for the ON period if the pattern is used to control Output Port 4. Note: The frequency can be set in supported steps from just a few Hz to many kHz.

1. 50 ms or 1 second resolution depending on the mode (fast tick mode or slow tick mode).

Table 16. Timers and counters description

Table 17. gives a visual description of the parameters given in Table 16. above.

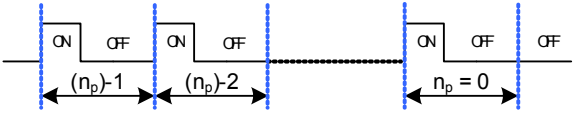
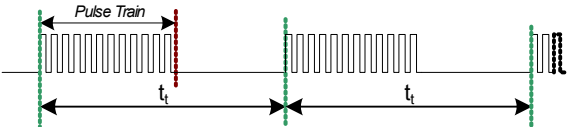
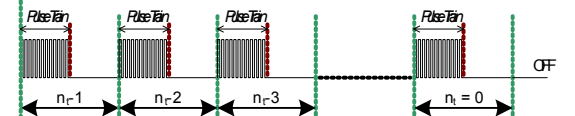
Parameter	Wave form	Description
$[t_{p1}] [t_{p2}]$		Basic pulse pattern where $[t_{p1}]$ specifies the ON period and $[t_{p2}]$ specifies the OFF period
$[n_p]$		<i>Pulse Train</i> where the basic pulse pattern are repeated $[n_p]$ times
$[t_i]$		Consecutive <i>Pulse Trains</i> that are repeatedly started at interval off $[t_i]$ seconds
$[n_i]$		Consecutive <i>Pulse Trains</i> that are repeated $[n_i]$ number of times (at an interval of $[t_i]$ seconds).

Table 17. Visualization of the timers and counters

6.3.4.1 OSIG pattern generated in Fast Tick mode

If the user selects Fast Tick mode, the output pattern will be generated using 50 ms resolution on the timers: $[t_{p1}]$ and $[t_{p2}]$. The ON and OFF period could then be specified in the range from 50 ms to 12.75 s in 50 ms steps.

If nRF8002 is running patterns using Fast Tick mode the CPU needs to be active almost all the time, impacting current consumption. The only exception will be if there are periods longer than 1 sec where the output does not switch state.

Patterns that are setup to be repeated forever will be synced with the 1 sec tick. This means that there could be up to a 1 sec delay between the activation and the execution.

6.3.4.2 OSIG pattern generated in Slow Tick mode

If the user selects Slow Tick mode, the pattern will be generated using 1 sec resolution on the timers: $[t_{p1}]$ and $[t_{p2}]$. The ON and OFF period could then be specified in the range from 1 sec to 255 sec (that is 4 min 15 sec) in 1 sec steps.

Patterns running in Slow Tick mode will not need the CPU to be active all the time. How much the CPU is running depends on how often the pattern switches state between ON and OFF. A worst case scenario is if the CPU stays active for 1 second every time there is a transaction (ON-OFF or OFF-ON).

6.3.4.3 Examples using Fast Tick mode

In Fast Tick mode $[t_{p1}]$ / $[t_{p2}]$ are given in 50 ms resolution.

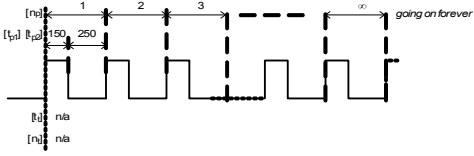
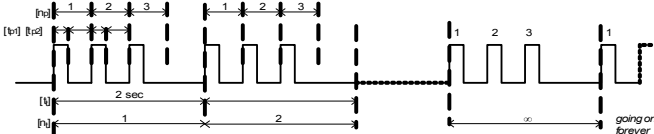
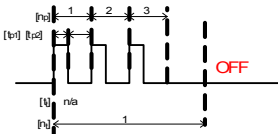
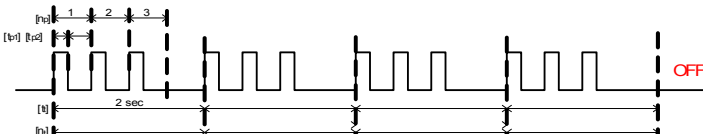
No	$[t_{p1}]$ / $[t_{p2}]$	$[n_p]$	$[t_t]$	$[n_t]$	Pattern
1	150 ms / 250 ms	∞	n/a	n/a	
2	150 ms / 250 ms	3	2 sec	∞	
3	150 ms / 250 ms	3	n/a	1	
4	150 ms / 250 ms	3	2 sec	4	

Table 18. Patterns using fast tick mode

6.3.4.4 Examples using Slow Tick mode

In Slow Tick mode $[t_{p1}]$ / $[t_{p2}]$ are given in 1 sec resolution.

No	$[t_{p1}]$ / $[t_{p2}]$	$[n_p]$	$[t]$	$[n_t]$	Pattern
1	1 sec / 2 sec	∞	n/a	n/a	
2	1 sec / 2 sec	3	15 sec	∞	
3	1 sec / 2 sec	3	n/a	1	
4	1 sec / 2 sec	3	15 sec	4	

Table 19. Patterns using slow tick mode

6.3.5 OSIG Activation (OSIG configuration)

nRF8002 has one OSIG Activation configuration for each of the events listed in [Table 14. on page 21](#). Each OSIG Activation can activate one or more of the output ports. OSIG patterns will be terminated if an Input event places the device into sleep.

As described in [Table 20](#), OSIG Activation contains individual setup for each of the four output ports. For each output port the user could select: Port Enable, OSIG Pattern number, and Inverted.

Port #	Port Enable	OSIG pattern	Inverted	Description
Output Port 1	X	9	-	Do action on Output port 1. Pattern 9, original waveform
Output Port 2	-	n/a	n/a	No action on Output port 2
Output Port 3	X	3	X	Do action on Output port 3. Pattern 3, inverted waveform
PWM	X	0	X	Do action on Output port 4. Special Pattern 0, inverted waveform

Table 20. Example of OSIG activation on each of the four output ports

6.3.5.1 Port Enable

Selects whether the actual output port should be handled by this event. Output ports that are not selected will not be affected by the actual event (that is, port status stays unchanged).

6.3.5.2 OSIG Pattern

For the output ports that are enabled, the OSIG Pattern index must be set. This selects, from the defined OSIG Patterns, which to use for the given output port.

6.3.5.3 Inverted

This parameter will, when it is enabled, invert the logical level on the selected OSIG Pattern output. This means that the ON periods will be converted to OFF periods and vice versa. For PWM, the inversion is the same and the PWM frequency will follow the ON period.

In [Table 21](#), the figure in the first row of the Waveform column shows a waveform where the `Inverted` parameter is disabled and the second row shows the same waveform but with the `Inverted` parameter enabled (True).

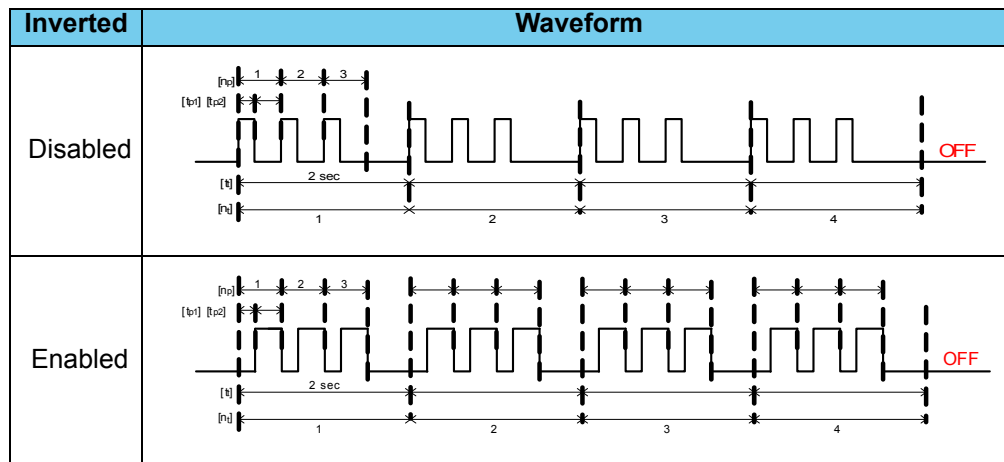


Table 21. Waveform of the OSIG pattern, not inverted and inverted

The parameter only affects the actual pattern. This means that before the pattern is started, both patterns have the level set to OFF. This will also be the case after the pattern is finished (Pulse Train repeated four times). Then the output level is set to OFF.

When the pattern starts, the non-inverted pattern starts with an ON period while the Inverted pattern starts with an OFF period. The output level will be kept OFF between consecutive Pulse Trains. This will be the same for both inverted and non-inverted outputs.

It also inverts the output level at the end of a Pulse Train before it starts the next Pulse Train.

Notice that we here only describe the logical value ON and OFF not the voltage. The voltage set on the output port will depend on the active high/low settings for the output ports.

6.4 Configuration in production

This section describes the nRF8002 command line tool for configuration in production, suitable for nRF8002 configuration in a production line, and the protocol used by it. Both a precompiled version as well as full source code of this tool is available through the nRFGo Studio.

In nRFGo Studio the user can, instead of downloading the setup directly to nRF8002, select to generate a setup file. This file is used as an input to the production tool. The protocol used by the production tool to download the configuration is described in the nRFGo Studio Help file.

nRF8002 is configured by sending packets to it over a UART. It is a basic protocol based on packets protected with a CRC. If the CRC check fails, a packet is retransmitted. Source code and a precompiled exe file are provided which implements this protocol.

6.4.1 Command line tool for configuration in production

The Command line tool is an executable file that could be used to download the configuration to the nRF8002. It takes two input parameters. The first specifies which serial port to use; the second gives the file to be downloaded (see description below for details on how to use).

ubblue_cfg.exe <port> <file>

<port>: Is written like "COMx", where the x represents a number between 1 and 9

<file>: Is the filename including the path to the file containing the configuration (generated by nRFGo Studio)

An example could look like this: **ubblue_cfg.exe com2 c:\nRFGoStudio\filename.ext**

The file to be downloaded by the command line tool has to be generated by nRFGo Studio. Use the option to generate a file instead of downloading directly to the nRF8002 device. The configuration file could be setup to be temporary (i.e. only uploaded to RAM) or permanent (i.e. uploaded to RAM + OTP). The temporary upload will get lost when the power is cycled.

From nRFGo Studio you can click on "Get source code for production tool" to get the source code and a precompiled executable file.

6.4.2 Command line tool source code

The source code is organized as a Microsoft Visual Studio project (ref: ...**\productionTool\ubblue_setup\Prj\ubblue_cfg.sln**).

The function to call is located in the file ...**\ubblue_setup\Src\ubblue_cfg.c** and is named **ubblue_setup_nrf8002_cfg_send()**. See description below for details on the parameters.

```
ubblue_setup_nrf8002_cfg_send(void* output,  
                               uint8_t* p_serial_fname,  
                               uint16_t dlen,  
                               uint8_t* p_data);
```

- output FILE* Stream where the function can output some debug information
- p_serial_fname String identifying the Comport.
- dlen Length of the p_data buffer.
- p_data Pointer to the buffer which nRFGo Studio saves to the production config file.

6.4.3 Protocol Stack

The nRF8002 configuration process is performed using the protocol stack as shown in [Figure 10](#).

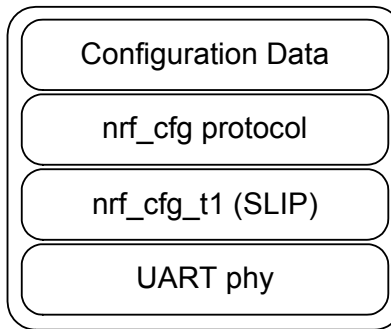


Figure 10. The protocol stack

Each of the layers is further described below.

6.4.3.1 Configuration Data

This is the actual data that nRFgo Studio produces and puts in the production configuration file.

6.4.3.2 nrf_cfg protocol

This is a relatively simple protocol with the following features:

- Client (PC) - Server (nRF8002) command/response operation
- Support for 64-byte packets
- Integrated length field to avoid relying on frame sizes
- Sequence number based retransmissions
- Full CRC-16-CCITT based error checks

The nrf_cfg client (PC) sends commands to the nrf_cfg server (nRF8002) one at a time, and waits for a response from it. Retransmissions may be necessary if the physical layer is unreliable and the retransmission limit is set by the client implementation.

Name	Size	Description
Header		
Length	1	Packet length excluding itself
SeqNo	1	Sequence number
Data		
Configuration Data	0..60	Serialized configuration data
CRC		
CRC	2	CRC-16-CCITT covering header and data

Table 22. Command Frame

Name	Size	Description
Header		
Length	1	Packet length excluding itself
SeqNo	1	Sequence number
Status	1	Status code
Data		
CmdCRC	2	Original command CRC
CRC		
CRC	2	CRC-16-CCITT covering header and data

Table 23. Response Frame

6.4.3.3 nrf_cfg_tl (SLIP)

All **nrf_cfg** commands and responses are sent with a standard SLIP framing, based on RFC 1055. The Escape and End characters are defined in **nrf_cfg_tl_types.h**, since those differ from the standard IETF ones defined in RFC 1055:

Code	Value
SLIP_END	0xFF
SLIP_ESC	0xFE
SLIP_ESC_END	0xFC
SLIP_END_ESC	0xFD

Table 24. Slip framing

6.4.3.4 UART Physical layer

This is a standard UART without flow control. For more information about the parameters, see section [12.3 on page 40](#).

7 Direct Test Mode (DTM)

RF PHY testing of the nRF8002 device can be performed using the embedded *Bluetooth* low energy Direct Test Mode (DTM).

When active, the nRF8002 *Bluetooth* low energy radio is controlled by 2-byte commands on the 2-wire UART interface. See section [12.3 on page 40](#) for a description of the UART interface characteristics.

The DTM has two modes of operation; a transmit test mode and a receive test mode. In transmit test mode, nRF8002 generates a predefined set of test packets. In receive test mode, nRF8002 counts the number of test packets received from a dedicated RF transceiver tester¹.

The nRFgo Studio enables RF transceiver testing using the DTM. For more information, visit www.nordicsemi.com.

Note: All *Bluetooth* low energy end products must include access to the DTM UART interface for end-product qualification testing of the RF transceiver layer.

7.1 Activating and deactivating Direct Test Mode

The DTM is activated automatically when a non-configured nRF8002 device is reset. The UART is then ready to receive DTM test commands.

The nRF8002 remains in DTM until power is disconnected. As the DTM current consumption is in the order of 5 mA, any battery supply should be disconnected in order to avoid draining the battery when the device is not in use.

7.2 Transmitter constant carrier operation

The DTM can also be used to initiate a constant un-modulated carrier mode on the specified RF channel. When initiated, this mode enables easy tuning of antenna and matching network. This is a Nordic Semiconductor proprietary feature and is not described in the *Bluetooth* DTM specification.

To initiate the constant carrier mode, the PKT field in the LSByte of the DTM command must be set to binary value 11.

1. A proprietary tester can be implemented by means of a nRF8002 device setup in DTM (transmit mode), sending test packets to a nRF8002 Device Under Test (DUT). Correspondingly, a nRF8002 device set up in receive test mode can be used as a tester, counting test packets received from a nRF8002 DUT.

8 Absolute maximum ratings

Maximum ratings are the extreme limits to which nRF8002 can be exposed without permanently damaging it. Exposure to absolute maximum ratings for prolonged periods of time may affect nRF8002's reliability.

[Table 25](#) specifies the absolute maximum ratings for nRF8002.

Parameter	Minimum	Maximum	Unit
Supply voltages			
VDD	-0.3	+3.6	V
VSS		0	V
I/O pin voltage			
V _{IO}	-0.3	VDD+0.3 V	V
Temperatures			
Storage temperature	-40	+125	°C

Table 25. Absolute maximum ratings

Attention!

Observe precaution for handling Electrostatic Sensitive Device. HBM (Human Body Model): Class 2	
---	--

9 Operating conditions

The operating conditions are the physical parameters that nRF8002 can operate within. The operating conditions for nRF8002 are defined in [Table 26](#).

Symbol	Parameter (condition)	Notes	Min	Nominal	Max	Units
VDD	Supply voltage		1.9	3.0	3.6	V
t _{R_VDD}	Supply rise time (0 to 1.9 V)		1 μs		50 ms	μs and ms
T _A	Operating temperature		-25		+70	°C

Table 26. Operating conditions

10 Electrical specifications

This chapter contains electrical specifications for signal levels, radio parameters and, current consumption. The test levels referenced are defined in [Table 27](#).

Test level	Description
I	By design (simulation, calculation, specification limit)
II	Prototype verification @ EOC ¹
III	Verified @ EOC in accordance with JEDEC47 (3 lots x 10 samples)
IV	100% test @ NOC ²

1. Extreme Operation Conditions
2. Nominal Operating Conditions

Table 27. Test level definitions

10.1 Digital I/O signal levels

The digital I/O signal levels are defined in [Table 28](#). The operating conditions are: VDD = 3.0 V, T_A = -25 to +70 °C (unless otherwise noted).

Symbol	Parameter (condition)	Test level	Min	Nom	Max	Unit
V _{IH}	Input high voltage	I	0.7×VDD		VDD	V
V _{IL}	Input low voltage	I	VSS		0.3×VDD	V
V _{OH}	Output high voltage (I _{load} ≥ I _{OH})	II	VDD-0.3			V
V _{OL}	Output low voltage (I _{load} ≤ I _{OL})	II			0.3	V
I _{OH}	Output high level current, standard drive strength (VDD ≥ V _{OH} ≥ VDD -0.3 V)	II	-0.5 ¹		0	mA
I _{OH}	Output high level current, high drive strength ² (VDD ≥ V _{OH} ≥ VDD -0.3 V)	II	-5 ¹		0	mA
I _{OL}	Output low level current, standard drive strength (0.3 V ≥ V _{OL} ≥ VSS)	II	0		0.5 ³	mA
I _{OL}	Output low level current, high drive strength ² (0.3 V ≥ V _{OL} ≥ VSS)	II	0		5 ³	mA

1. Current flowing out of the device has a negative value.
2. Maximum number of pins with high drive strength is 3.
3. Current flowing in to the device has a positive value.

Table 28. Digital inputs/outputs

10.2 Radio characteristics

nRF8002 electrical characterization is defined in [Table 31](#). The operating conditions are:
VDD = 3.0 V, T_A = -25 to +70 °C (unless otherwise noted).

Symbol	Parameter (condition)	Test level	Notes	Min	Nom	Max	Unit
f _{OP}	Frequency operating range	I		2402		2480	MHz
f _{XTAL}	Crystal frequency	I			16		MHz
Δf	Frequency deviation	I			250		kHz
R _{GFSK}	On air data rate	I			1		Mbps
PLL _{RES}	RF channel spacing	I			2		MHz

Table 29. Radio general electrical characteristics

Symbol	Parameter (condition)	Test level	Notes	Min	Nom	Max	Unit
P _{RF}	Maximum output power	I	1		0	4	dBm
P ₋₆	Output power setting				-6		dBm
P ₋₁₂	Output power setting				-12		dBm
P ₋₁₈	Output power setting				-18		dBm
BW _{20dB}	20 dB signal bandwidth	I			670		kHz
P _{RF1.1}	1st adjacent channel power	I			-25		dBc
P _{RF2.1}	2nd adjacent channel power	I			-40		dBc

1. Antenna load impedance = 15 Ω + j88

Table 30. Radio transmitter electrical characteristics

Symbol	Parameter (condition)	Test level	Notes	Min	Nom	Max	Unit
P _{RX max}	Maximum input signal strength at PER ≤ 30.8%	I			0		dBm
P _{sens IT}	Receiver sensitivity: ideal transmitter	I			-87		dBm
P _{sens DT}	Receiver sensitivity: dirty transmitter	I	1		-86		dBm
C/I _{CO}	Co-channel rejection	I			13		dB
C/I _{1st}	Adjacent channel selectivity: 1 MHz offset	I	1.		7		dB
C/I _{2nd}	Adjacent channel selectivity: 2 MHz offset	I	1.		-23		dB
C/I _{3+n}	Adjacent channel selectivity: (3+n) MHz offset [n=0,1,2...]	I	1.		-51		dB
C/I _{Image}	Image frequency rejection	I	1. and 2		-26		dB
P _{IM}	IMD performance (P _{in} =64 dBm)	I	1.		-38		dBm

- As defined in *Bluetooth V4.0 Volume 6: Core System Package [Low Energy Controller Volume]*.
- Image frequency = f_{RX} + 4 MHz.

Table 31. Radio receiver electrical characteristics

10.3 Analog feature characteristics

Symbol	Parameter (condition)	Test level	Notes	Min	Nom	Max	Unit
B _{range}	Battery Monitor Range	I		1.9		3.6	V
B _{acc}	Battery Monitor Accuracy	I		-0.05		0.05	V

Table 32. Analog feature electrical characteristics

11 Current consumption

A typical *Bluetooth* low energy application has a low duty cycle and limited data transfer. To predict battery lifetime, it is important to understand how the chosen hardware and protocol parameters influence the overall power consumption.

Symbol	Parameter (condition)	Test level	Min	Nom	Max	Unit
I_{peak}	Peak current in any mode	I		14.5		mA
$I_{\text{fast_adv}}$	Average advertise current consumption for Fast Adv. (adv_int = 30 ms)	I		760		μA
$I_{\text{slow_adv}}$	Average advertise current consumption for Slow Adv. (adv_int = 1 sec)			25		μA
I_{conn}	Average connection current consumption, no I/O activity (connection interval = 1 sec)	I		16		μA

Table 33. nRF8002 current consumption

The nRFgo Studio Current Consumption Calculator can be used to calculate average power consumption, and battery lifetime for different scenarios.

12 Hardware description

12.1 Reset

The RESET line should be held low for a minimum duration of 200 ns for the nRF8002 to reset.

12.2 16 MHz oscillator

The 16 MHz crystal oscillator is designed for use with an AT-cut quartz crystal in parallel resonant mode. To achieve correct oscillation frequency, the load capacitance must match the specification in the crystal data sheet. [Figure 11.](#) shows how the crystal is connected to the 16 MHz crystal oscillator.

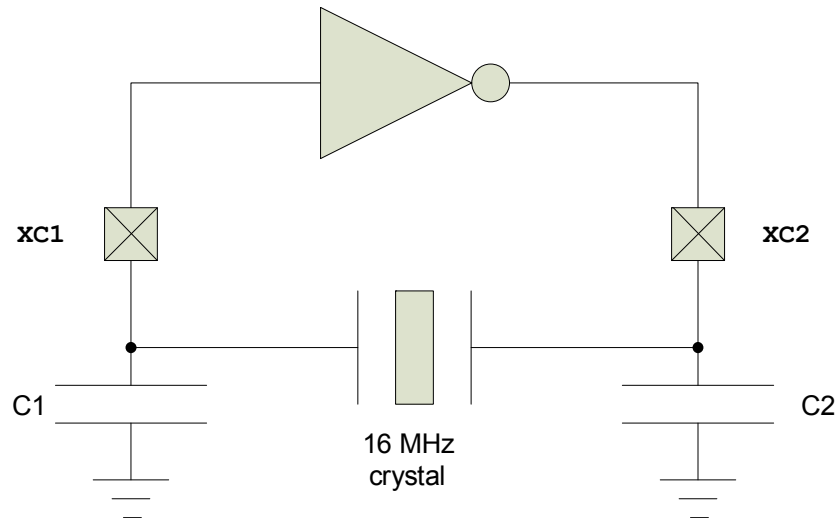


Figure 11. Circuit diagram of nRF8002's 16 MHz crystal oscillator

The load capacitance is the total capacitance seen by the crystal across its terminals and is given by:

$$C_{load} = \frac{(C1' \times C2')}{(C1' + C2')}$$

$$C1' = C1 + C_{pcb1} + C_{pin}$$

$$C2' = C2 + C_{pcb2} + C_{pin}$$

C1 and C2 are ceramic SMD capacitors connected between **xc1** and **xc2** and ground. C_{pcb1} and C_{pcb2} are stray capacitances on the PCB. C_{pin} is the input capacitance on the **xc1** and **xc2** pins, typically 1 pF. C1 and C2 should be of the same value.

12.2.1 Internal 32.768 kHz RC oscillator

The internal 32.768 kHz RC oscillator which provides the protocol and application timing for the connection to the peer device is an internal oscillator. No external components or configuration is required.

12.3 UART interface characteristics

The UART interface used for device configuration and Direct Test Mode (DTM) operation has the following features:

- 2-wire UART interface (TXD/RXD)
- Baud rate: 19200
- 8 data bits
- No parity
- 1 stop bit
- No flow control (meaning no RTS/CTS)

UART interface pins are described in [Figure 2. on page 7](#) and [Table 1. on page 8](#).

12.4 Antenna matching and balun

The ANT1 and ANT2 pins provide a balanced RF connection to the antenna. The pins must have a DC to VDD_PA, either through an RF choke or through the center point in a balanced dipole antenna. A load impedance at ANT1 and ANT2 of 15 Ω and j88 Ω is recommended for maximum output. A load impedance of 50 Ω can be obtained by fitting a simple matching network between the load and the ANT1 and ANT2 pins.

12.5 PCB layout and decoupling guidelines

A well designed PCB is necessary to achieve good RF performance. A poor layout can lead to loss of performance or functionality. A fully qualified RF-layout for the nRF8002 and its surrounding components, including matching networks, can be downloaded from www.nordicsemi.com.

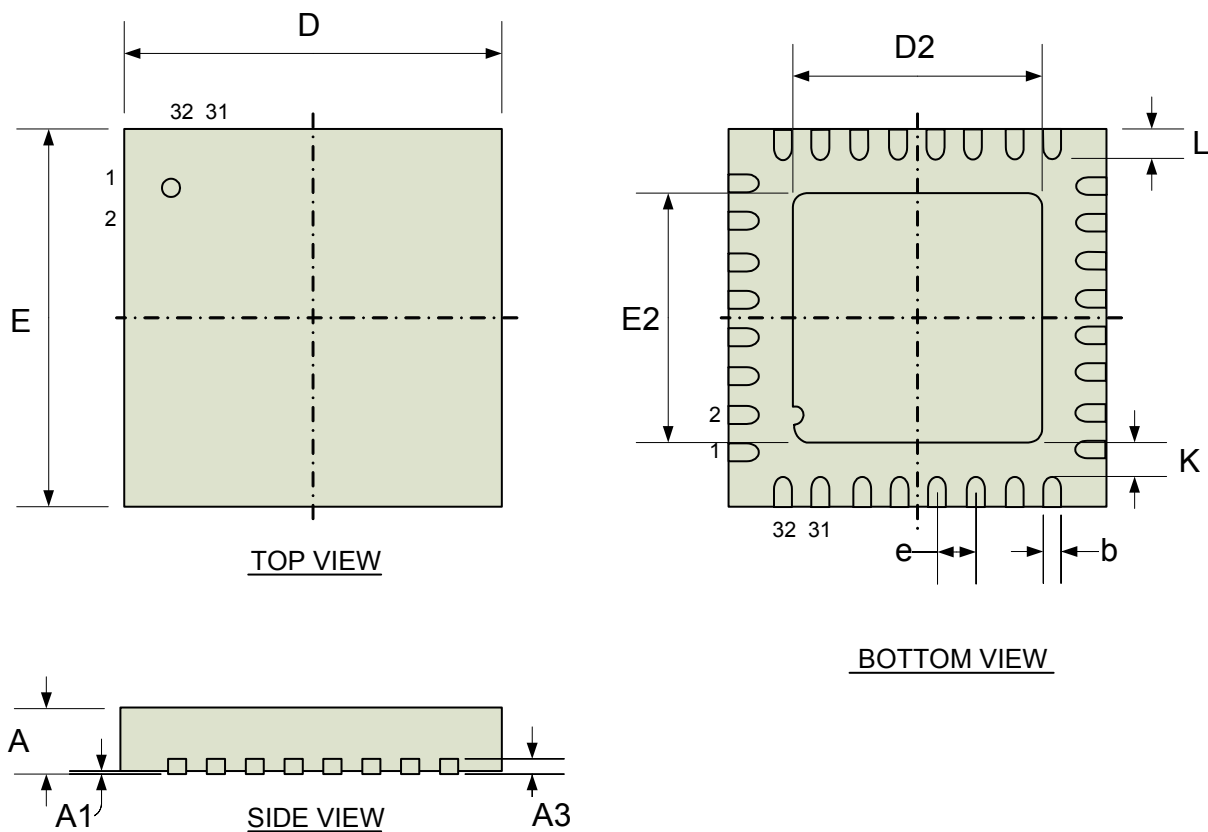
A PCB with a minimum of two layers including a ground plane is recommended for optimum performance. The nRF8002 DC supply voltage should be decoupled as close as possible to the VDD pins with high performance RF capacitors. See the schematics layout in chapter [15 on page 43](#) for recommended decoupling capacitor values. The nRF8002 supply voltage should be filtered and routed separately from the supply voltages of any digital circuitry.

Long power supply lines on the PCB should be avoided. All device grounds, VDD connections and VDD bypass capacitors must be connected as close as possible to the nRF8002 IC. For a PCB with a topside RF ground plane, the VSS pins should be connected directly to the ground plane. For a PCB with a bottom ground plane, the best technique is to have via holes as close as possible to the VSS pads. A minimum of one via hole should be used for each VSS pin.

Full swing digital data or control signals should not be routed close to the crystal or the power supply lines.

13 Mechanical specifications

nRF8002 is packaged in a QFN32 5×5×0.85 mm, 0.5 mm pitch.



Package	A	A1	A3	b	D, E	D2, E2	e	K	L	
QFN32	0.80	0.00		0.18	4.9	3.50		0.20	0.35	Min
	0.85	0.02	0.20	0.25	5.0	3.60	0.5		0.40	Nom
	0.90	0.05		0.30	5.1	3.70			0.45	Max

Table 34. QFN32 dimensions in mm

14 Ordering information

14.1 Package marking

N	R	F		B	X
8	0	0	2		
Y	Y	W	W	L	L

14.2 Abbreviations

Abbreviation	Definition
8002	Product number
B	Build Code, that is, unique code for production sites, package type and test platform
X	"X" grade, that is, Engineering Samples (optional)
YY	Two-digit year number
WW	Two-digit week number
LL	Two-letter wafer-lot number code

Table 35. Abbreviations

14.3 Product options

14.3.1 RF silicon

Ordering code	Package	Container	MOQ ¹	MSL ²
nRF8002-R1Q32-R	5x5 mm 32-pin QFN, lead free (green)	13" Reel	4000	2
nRF8002-R1Q32-R7	5x5 mm 32-pin QFN, lead free (green)	7" Reel	1500	2
nRF8002-R1Q32-T	5x5 mm 32-pin QFN, lead free (green)	Tray	490	2

1. Minimum Order Quantity
2. Moisture Sensitivity Level

Table 36. nRF8002 RF silicon options

14.3.2 Development tool

Type Number	Description
nRF8002-DK	nRF8002 Development Kit

Table 37. nRF8002 solution option

15 Example application circuitry

15.1 PCB guidelines

To ensure optimal performance it is essential that you follow the schematics- and layout references closely. Especially in the case of the antenna matching circuitry (components between device pins ANT1,ANT2, VDD_PA and the antenna), any changes to the layout can change the behavior, resulting in degradation of RF performance or a need to change component values. All the reference circuits are designed for use with a 50 ohm single end antenna. See [Section 12.5 on page 40](#) for more information.

15.2 Schematic nRF8002 example application

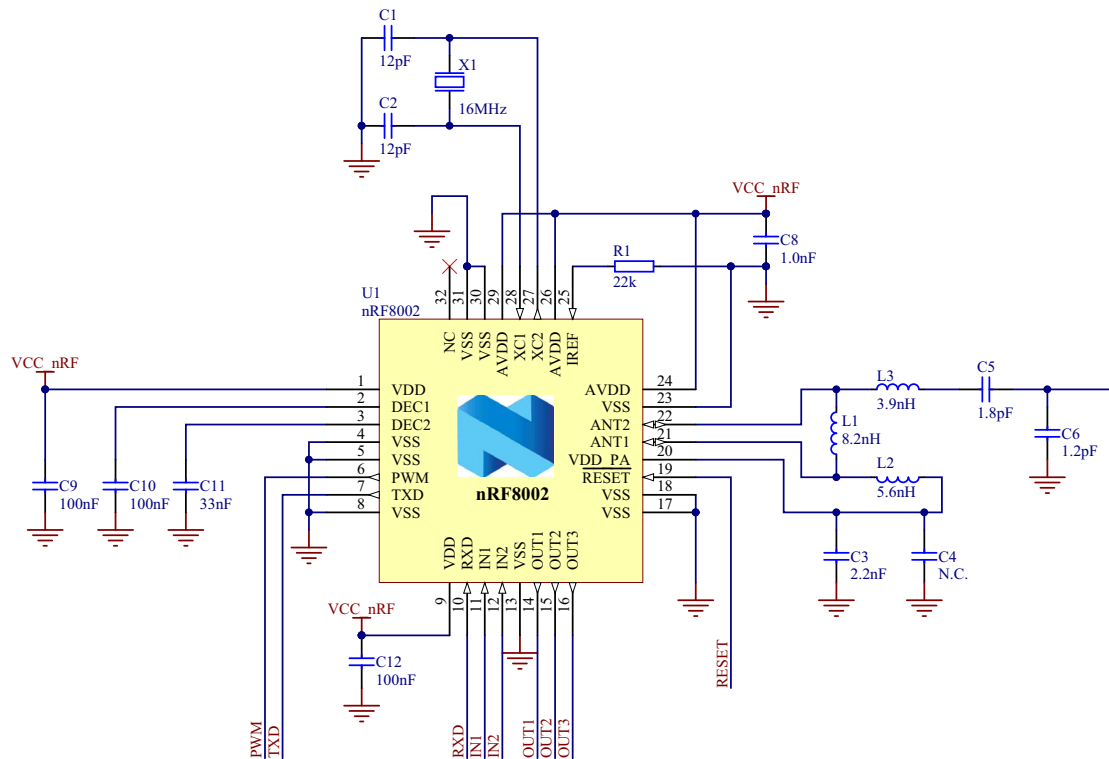
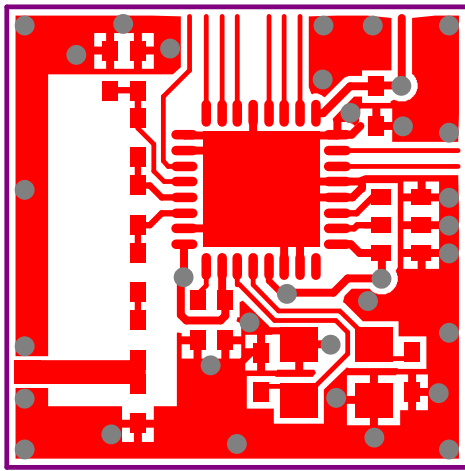
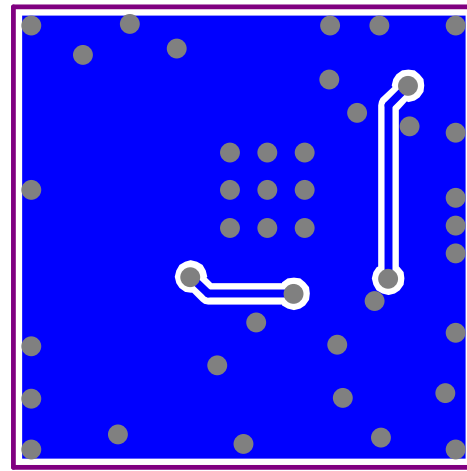


Figure 12. Schematic nRF8002 example application

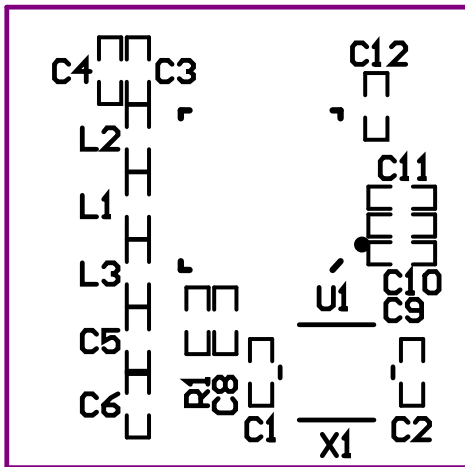
15.3 PCB layout nRF8002 example application



Top view



Bottom view



Top silk screen

No components
In bottom layer

Figure 13. PCB layout nRF8002 example application

15.4 Bill of Materials nRF8002 example application

Designator	Value	Footprint	Comment
C1, C2	12 pF	0402	Capacitor, NP0 $\pm 2\%$
C3	2.2 nF	0402	Capacitor, X7R $\pm 10\%$
C4	NA	0402	Not mounted
C5	1.8 pF	0402	Capacitor, NP0 ± 0.1 pF
C6	1.2 pF	0402	Capacitor, NP0 ± 0.1 pF
C8	1.0 nF	0402	Capacitor, X7R $\pm 10\%$
C9, C10, C12	100 nF	0402	Capacitor, X7R $\pm 10\%$
C11	33 nF	0402	Capacitor, X7R $\pm 10\%$
L1	8.2 nH	0402	High frequency chip inductor $\pm 5\%$
L2	5.6 nH	0402	High frequency chip inductor $\pm 5\%$
L3	3.9 nH	0402	High frequency chip inductor $\pm 5\%$
R1	22 k Ω	0402	Resistor, $\pm 1\%$, 0.063 W
U1	nRF8002	QFN32	QFN32 5×5 mm package
X1	16 MHz	3.2 × 2.5 mm	SMD-3225, 16 MHz, CL=9 pF, ± 40 ppm
PCB substrate	FR4 laminate		2 layer, thickness 1.6 mm

Table 38. Bill of materials nRF8002 example application

16 Glossary

Term	Description
ACI	Application Controller Interface
BTLE	<i>Bluetooth</i> Low Energy
CCCD	Client Characteristic Configuration Descriptor
CSRK	Connection Signature Resolving Key
DTM	Direct Test Mode
EDIV	Encrypted Diversifier
EOC	Extreme Operating Conditions
EP-QDL	End Product Qualified Design Listing
ESR	Equivalent Series Resistance
GAP	Generic Access Profile
GATT	Generic Attribute Profile
HV	Handle Value
IMD	Intermodulation Distortion
IRK	Identity Root Key
LTK	Long Term Key
MD	More Data
MOQ	Minimum Order Quantity
MCU	Micro Controller Unit
MSC	Message Sequence Chart
MSL	Moisture Sensitivity Level according to JEDEC classification
NOC	Nominal Operating Conditions
NVM	Non-Volatile Memory
OOR	Out Of Range
PCB	Printed Circuit Board
PDU	Protocol Data Unit
PHY	Physical
PICS	Protocol Implementation Conformance Statement
PUID	Personal User Interface Device
RF	Radio Frequency
RoHS	Restriction of Hazardous Substances
SDK	Software Development Kit
UART	Universal Asynchronous Receiver Transmitter
VM	Volatile Memory